



## REVISION HISTORY

| ECO | REV | DESCRIPTION   | APP. ENG. | DATE     |
|-----|-----|---------------|-----------|----------|
| -   | 1   | 1ST PROTOTYPE | ERIC H.   | 10-19-18 |

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS ON JP1 AND JP2.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. DO NOT BREAK THIS SCORE LINE AFTER ASSEMBLY.

## APPROVALS

PCB DES. KIM T.

APP ENG. ERIC H.

SCALE = NONE



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TITLE: TOP ASSEMBLY DRAWING  
IEEE 802.3bt COMPLIANT, LTPoE++  
INTEROPERABLE POWERED DEVICE

|             |  |           |
|-------------|--|-----------|
| SIZE<br>N/A | IC NO.<br>LT4293IDD, LT4321IUF<br>DEMO CIRCUIT 2911A | REV.<br>1 |
|-------------|--|-----------|

FILENAME: DC2911A-1.PCB

SHT 1 OF 2